

BOARD PACKAGE DOCUMENTS

FOLDERS:

Assembled_Pics/

3D renders of what assembled, finished board should appear as

Assembly_Drawings/

Location of components on top and bottom of board. Drawings include both top and bottom of board, and identified by reference designator and component value

BOM/

Bill of Materials of components to be installed on board. Two BOMs, one is sorted by reference designator, one is by component to aid in purchasing

DrillFiles/

Plated and non plated holes in separate files

Gerbers/

F.Cu	Top copper
In1.Cu	Inner copper layer #1
In2.Cu	Inner copper layer #2
In3.Cu	Inner copper layer #3
In4.Cu	Inner copper layer #4
B.Cu	Bottom copper
B.Adhes	Bottom Adhesive for SMD components
F.Paste	Top solder paste stencil
B.Paste	Bottom solder paste stencil
F.SilkS	Top silk screen
B.SilkS	Bottom silk screen
F.Mask	Top solder mask
B.Mask	Bottom solder mask
Edge Cuts	Board outline milling

Pick-n-Place_Files/

component position files, top and bottom of board